



# STPS5L25B/B-1

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	5 A
$V_{RRM}$	25 V
$T_j(max)$	150°C
$V_F(max)$	0.35 V

### FEATURES AND BENEFITS

- VERY LOW FORWARD VOLTAGE DROP FOR LESS POWER DISSIPATION AND REDUCED HEATSINK
- OPTIMIZED CONDUCTION/REVERSE LOSSES TRADE-OFF WHICH MEANS THE HIGHEST EFFICIENCY IN THE APPLICATIONS
- HIGH POWER SURFACE MOUNT MINIATURE PACKAGE
- AVALANCHE RATED

### DESCRIPTION

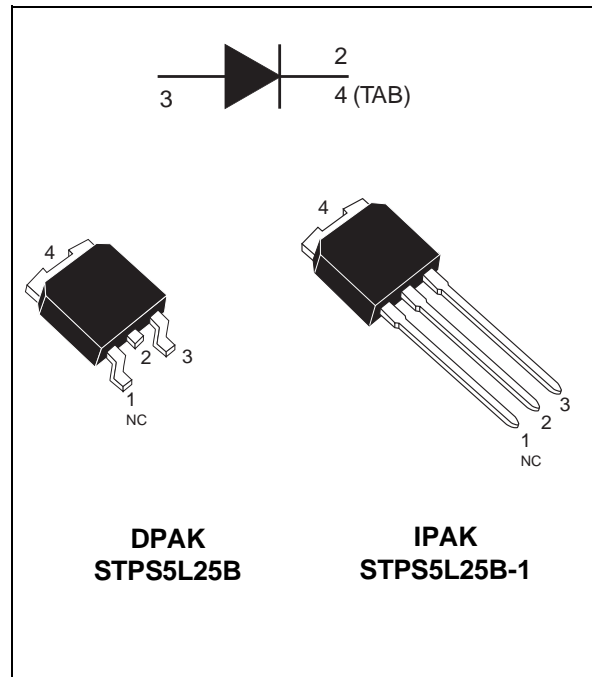
Single Schottky rectifier suited to Switched Mode Power Supplies and high frequency DC to DC converters.

This device is especially intended for use as a Rectifier at the secondary of 3.3V SMPS units.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	25	V
$I_{F(RMS)}$	RMS forward current	7	A
$I_{F(AV)}$	Average forward current	$T_c = 145^\circ\text{C} \delta = 0.5$	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms Sinusoidal}$	A
$I_{RRM}$	Repetitive peak reverse current	$t_p = 2 \mu\text{s square } F = 1\text{kHz}$	A
$I_{RSM}$	Non repetitive peak reverse current	$t_p = 100 \mu\text{s square}$	A
$T_{stg}$	Storage temperature range	- 65 to + 150	°C
$T_j$	Maximum operating junction temperature *	150	°C
$dV/dt$	Critical rate of rise of reverse voltage	10000	V/ $\mu\text{s}$

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  thermal runaway condition for a diode on its own heatsink



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## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	2.5	$^{\circ}\text{C}/\text{W}$

## STATIC ELECTRICAL CHARACTERISTICS

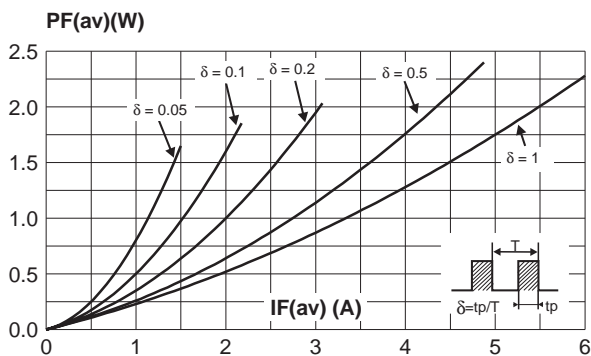
Symbol	Tests Conditions	Tests Conditions	Min.	Typ.	Max.	Unit	
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			350	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			55	115	$\text{mA}$
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 5\text{ A}$			0.47	V
		$T_j = 125^{\circ}\text{C}$			0.31	0.35	
		$T_j = 25^{\circ}\text{C}$	$I_F = 10\text{ A}$			0.59	
		$T_j = 125^{\circ}\text{C}$			0.41	0.50	

Pulse test : \*  $t_p = 380\ \mu\text{s}$ ,  $\delta < 2\%$

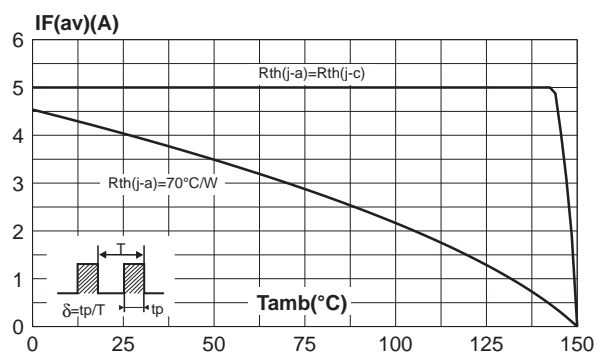
To evaluate the maximum conduction losses use the following equation :

$$P = 0.2 \times I_{F(AV)} + 0.030 I_{F(RMS)}^2$$

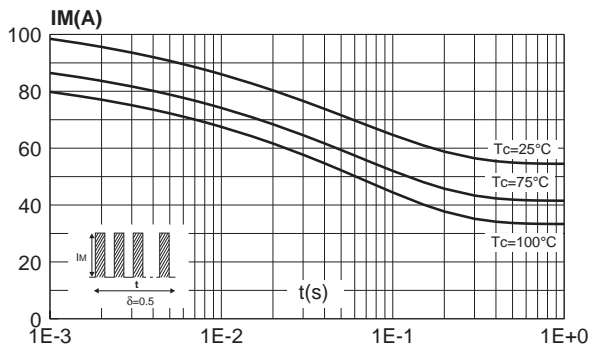
**Fig. 1:** Average forward power dissipation versus average forward current.



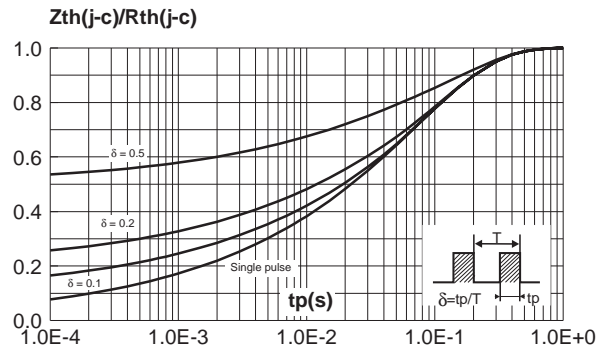
**Fig. 2:** Average forward current versus ambient temperature ( $\delta=0.5$ ).



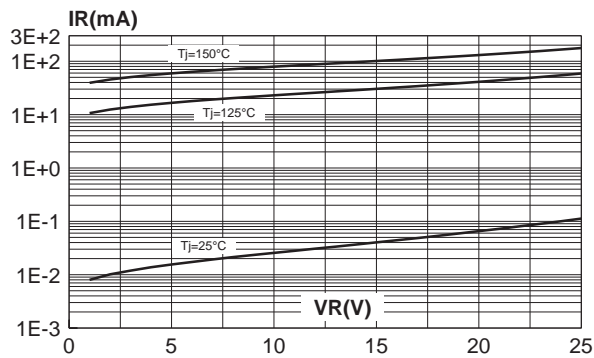
**Fig. 3:** Non repetitive surge peak forward current versus overload duration (maximum values).



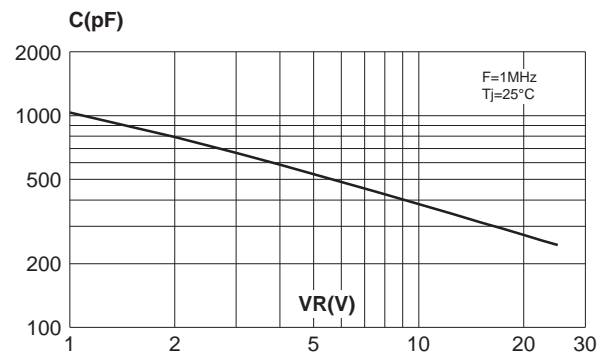
**Fig. 4:** Relative variation of thermal impedance junction to case versus pulse duration.



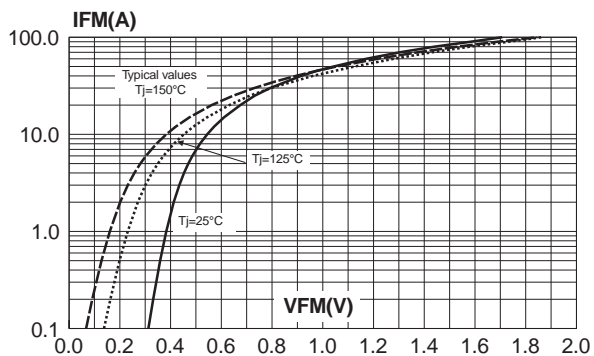
**Fig. 5:** Reverse leakage current versus reverse voltage applied (typical values).



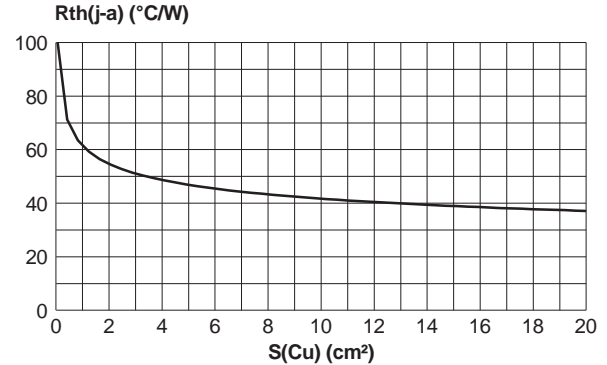
**Fig. 6:** Junction capacitance versus reverse voltage applied (typical values).



**Fig. 7:** Forward voltage drop versus forward current (maximum values).

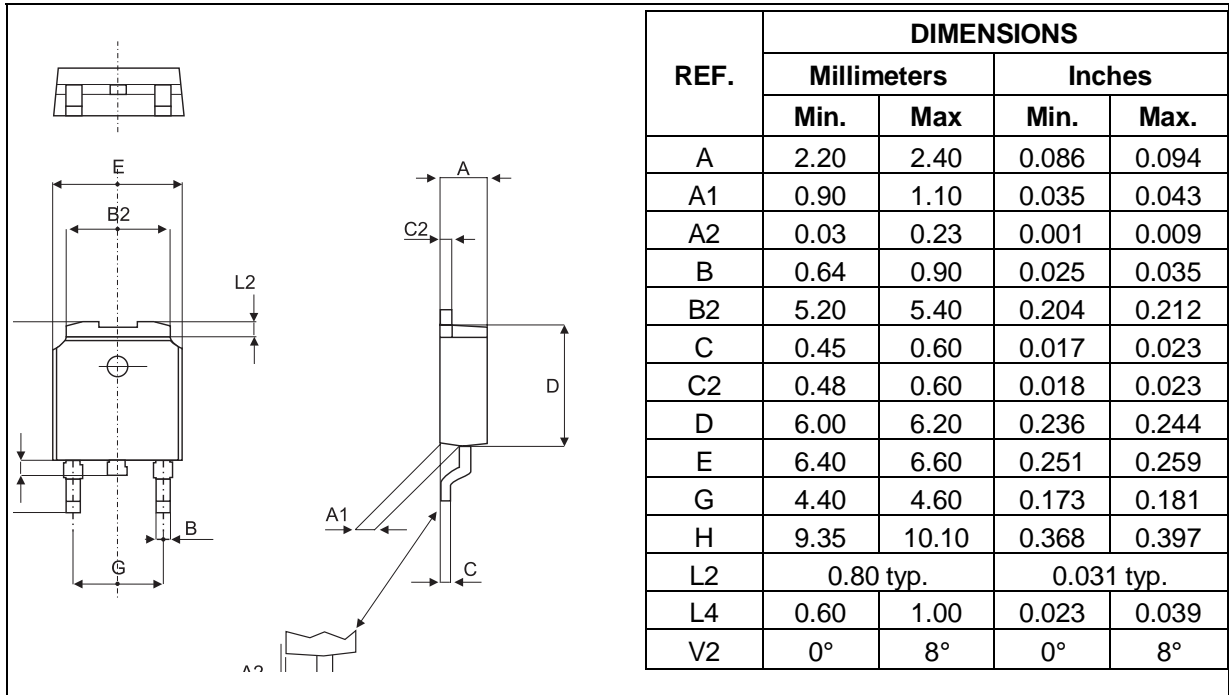


**Fig. 8:** Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35µm).

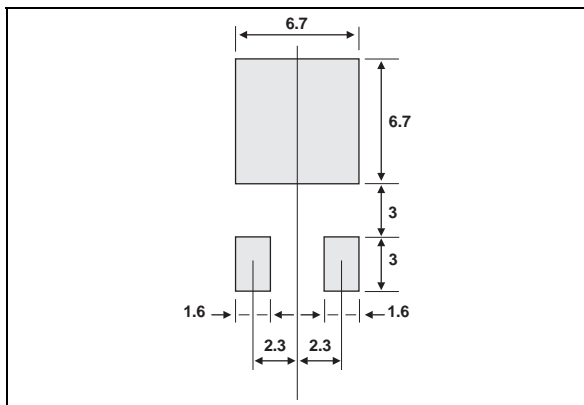


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## PACKAGE MECHANICAL DATA DPAK



### FOOT PRINT DIMENSIONS (in millimeters)



**PACKAGE MECHANICAL DATA**  
**IPAK**

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.035	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039
V1		10°			10°	

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS5L25B	STPS5L25B	DPAK	0.30g	75	Tube
STPS15LB-TR	STPS5L25B	DPAK	0.30g	2500	Tape & reel
STPS5L25B-1	STPS5L25B	IPAK	0.35g	75	Tube

■ Epoxy meets UL94,V0

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